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MT29F384G08EBHBBJ4-3R

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SIM MODELS &
SOFTWARE

ROHS
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& SUPPORT

PARTS WITH THE SAME
DATA SHEET (4)

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TO BUY

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Data Sheet Variance



MT29F[384G_768G_1T2_1HT_3T_6T] Fortis Flash TLC DSV

MT29F[384G_768G_1T2_1HT_3T_6T] Fortis Flash TLC DSV

3D NAND
China
NAND Flash
Taiwan
TLC NAND
USA

File Type: PDF

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Data Sheet



B0KB 384Gb 768Gb 1T2 1HTb 3Tb 6Tb sync NAND Fortis datasheet

B0KB 384Gb 768Gb 1T2 1HTb 3Tb 6Tb sync NAND Fortis datasheet

NAND Flash
TLC NAND

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Data Sheet Variance



MT29F[384G_768G_1T2_1HT] TLC DSV

MT29F[384G_768G_1T2_1HT] TLC DSV

3D NAND
China
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TLC NAND
USA

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Specs

Orderable Parts for: MT29F384G08EBHBBJ4-3R

SEE ALL TLC NAND PARTS

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
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MT29F384G08EBHBBJ4-3R:B	Production	N/A	NW851	N/A	N/A	No		N/A
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Detailed Specifications

Density	384Gb	Status	Production	NAND Type	3D	RoHS	Yes
Width	x8	Voltage	3.3V	Package	VBGA	Pin Count	132-ball
MT/s	667 MT/s	I/O	Common				

Sim Models & Software

Sim Models

HSpice

B0KB HSPICE (ZIP)

NAND Flash
TLC NAND

B0KB 384Gb 768Gb 1HTb 3Tb 6Tb sync NAND - HSPICE Rev 2.0

File Type: ZIP

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IBIS

B0KB IBIS (ZIP)

NAND Flash
TLC NAND

B0KB 384Gb 768Gb 1HTb 3Tb 6Tb sync NAND - IBIS Rev 2.0

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RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

MT29F384G08EBHBBJ4 3R

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

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Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

[See All TLC NAND Documentation](#)

Technical Notes

SEARCH (2) TLC NAND TECHNICAL NOTES

Technical Notes

TN-00-33: Power Integrity Simulation with IBIS 5.0 Models (PDF)

(TN-00-33) This technical note describes the new features in IBIS 5.0 enabling PI simulation. It also provides an overview of some of the modeling accuracy challenges and compares SSO simulation results using various electronic design automation (EDA) software tools.

File Type: PDF

Updated: 01/25/2016

3D NAND
DDR3 SDRAM
DDR4 SDRAM
DRAM
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Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

File Type: PDF

Updated: 02/14/2013

DDR SDRAM
DDR2 SDRAM
DDR3 SDRAM
DDR3L-RS
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SEARCH (2) TLC NAND TECHNICAL NOTES

Parts with the same Data Sheet (4)

MT29F384G08EBHBBJ4-3R (Current)	MT29F1T208ECHBBJ4-3R	MT29F1HT08EMHBBJ4-3R	MT29F3T08EUHBBM4-3R
Status	Production	Production	Production

Density	384Gb	2Tb	1Tb	3Tb
NAND Type	3D	3D	3D	3D
RoHS	Yes	Yes	Yes	Yes
Width	x8	x8	x8	x8
Voltage	3.3V	3.3V	3.3V	3.3V
Package	VBGA	VBGA	VBGA	LBGA
Pin Count	132-ball	132-ball	132-ball	132-ball
MT/s	667 MT/s	667 MT/s	667 MT/s	667 MT/s
I/O	Common	Common	Separate	Separate

Where to Buy

Orderable Parts

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29F384G08EBHBJ4-3R:B	Production	N/A	NW851	N/A	N/A	No		N/A

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